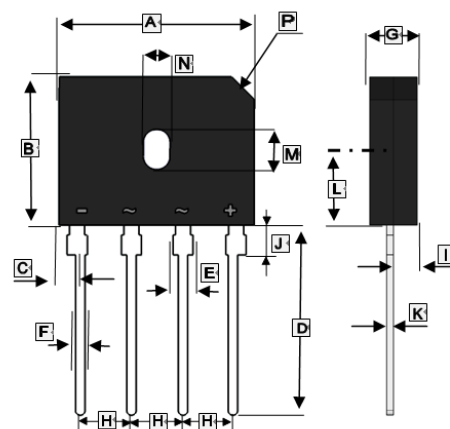


RoHS Compliant Product

FEATURES

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- Plastic material has Underwriters Laboratory flammability classification 94V-0
- Mounting position: Any
- These are Halogen & Pb Free components
- This series is UL recognized under Component Index, file number E255340

GBU



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	21.7	22.3	I	1.8	2.2
B	18.2	18.8	J	1.8	2.2
C	3.15	3.55	K	0.4	0.6
D	17.5	18.5	L	9.9	10.1
E	1.8	2.2	M	5.2	5.8
F	0.9	1.2	N	3.3	3.8
G	3.4	3.8	P	3 x 45°	
H	5	5.2			

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating 25°C ambient temperature unless otherwise specified. Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, de-rate current by 20%.)

Parameter		Symbol	Part Number				Unit
			S15GBU20-C	S15GBU40-C	S15GBU60-C	S15GBU80-C	
Maximum Recurrent Peak Reverse Voltage		V _{RRM}	200	400	600	800	V
Average Rectified Output Current @50HZ sine wave, R-load	T _C =100℃ (with heat sink)	I _O	15				A
	T _A =25℃ (without heat sink)		3.2				
Peak Forward Surge Current @ 50Hz sine wave, 1 cycle, T _A =25℃		I _{FSM}	200				A
Maximum Peak Forward Voltage ³		V _{FM}	1.1				V
Peak Reverse Current ²		I _{RRM}	10				μA
I ² t Rating for Fusing @1ms≤t<8.3ms, T _J =25℃,Rating of per diode		I ² t	166				A ² s
Mounting Torque @ Recommend torque:5kg·cm		TOR	8				Kg · cm
Dielectric Strength ¹		V _{dis}	2				kV
Typical Thermal Resistance (with heat sink)		R _{θJC}	5				℃/W
Typical Thermal Resistance(without heat sink)		R _{θJA}	23				℃/W
Typical Thermal Resistance(without heat sink)		R _{θJL}	4.2				℃/W
Operating and Storage temperature range		T _J ,T _{STG}	150, -40~150				℃

Notes :

1. Terminals to case · AC 1 minute
2. $V_{RM}=V_{RRM}$, Pulse measurement, Rating of per diode.
3. $I_{FM}=7.5\text{A}$, Pulse measurement, Rating of per diode

RATINGS AND CHARACTERISTIC CURVES

